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Sigrity Introduces Industry's First and Only Electrical and Thermal Co-Simulation Tool

Breakthrough PowerDC environment reduces time and effort for package and PCB designers, provides unparalleled accuracy to avoid smoke and fire failures in high-current designs

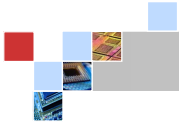
CAMPBELL, Calif. – January 28, 2010 – Sigrity, Inc., the market leader in signal and power integrity solutions, today announced PowerDC Thermal – new software that works in concert with the company's popular PowerDC Electrical simulation software to create the industry's first and only integrated thermal / electrical analysis environment for IC packages and printed circuit boards. Sigrity's breakthrough PowerDC Thermal product eliminates manual iterations between simulations with separate electrical and thermal tools, reduces time, and improves results convergence. It is ideal for avoiding field failures.

"Our customers find an increasing number of IC package and printed circuit board designs must safely operate at high current levels," said Dr. An-Yu Kuo, Director of Thermal and Mechanical Products of Sigrity. "The new Sigrity integrated thermal and electrical co-simulation environment provides unprecedented accuracy and ease of use for assessing potential field failure risks such as smoke and fire."

PowerDC thermal simulation fully considers both die heating and copper heating on the package and the board, and also takes temperature and location dependencies into account. Such precision simulation has not been available until now. Up to this point, design teams either have relied on overly pessimistic IPC peak temperature estimates, or thermal simulations that fail to fully account for the critical impact of high current density.

The new PowerDC automated environment with co-simulation maximizes accuracy by leveraging powerful electrical current density analysis, computing accurate thermal temperature distributions, and iterating on the combined effects. Thus, it fully considers factors such as the increasing electrical resistance at higher operating temperatures. Similarly, the converged results accurately reflect the impact of the increasing component power dissipation that takes place as temperatures rise.

Design files from all popular printed circuit board and IC package layout systems can be imported seamlessly into Sigrity's electrical / thermal co-simulation environment. In addition, the die model from popular IC design tools can be included.



Analysis can proceed on designs that are partially or fully placed and routed. The comprehensive simulations account for complex plane shapes, including cut-outs, wires, solder balls, solder bumps, and via structures to maximize accuracy. Sigrity's unique task-based workflow and the included constraint manager simplify set-up and make results easy to interpret. A range of reporting options as well as electrical and thermal color maps enable users to see the converged results so they can rapidly pinpoint improvement options.

Sigrity's new thermal and co-simulation capabilities are available as an add-on option to Sigrity's PowerDC – the industry leading DC analysis tool with a reputation for ease-of-use, fast throughput, accuracy and its patent-pending technology for automatically finding best remote sense locations. An electrical and thermal combined product also is available for new customers.

Pricing and Availability

The new PowerDC environment with DC analysis, thermal analysis and co-simulation capability is available on Windows and Linux platforms with annual prices starting at \$30,000. PowerDC Thermal also is available as an added option for currently licensed Sigrity PowerDC users. It adds thermal analysis and co-simulation to the present DC analysis capability; annual prices start at \$15,000.

About Sigrity

Sigrity, Inc., a privately held U.S. company incorporated in 1998, delivers advanced software solutions for package physical design and for analyzing power and signal integrity in chips, packages and printed circuit boards. Sigrity's patented electrical analysis methodologies run orders of magnitude faster than general-purpose electromagnetic tools, helping leading companies in the semiconductor, computer, graphics, communications and networking industries ensure high performance and reduce time to market. The company is headquartered in Campbell, Calif., with direct sales and global distribution through worldwide representatives. For more information about how to ensure operational designs by using Sigrity's package physical design and power and signal integrity analysis solutions, please visit: <http://www.sigrity.com>.

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